



Press-pack IGBT

Cutting edge technology for highly efficient performance.

Applications include: Renewables, VSC-HVDC, STATCOM, Circuit Breakers and MV Drives.



Designed primarily for electric utilities and medium voltage drive applications, Dynex Press-pack IGBT products incorporate state-of-the-art design and manufacturing technologies to ensure both high performance and reliability.

Dynex Press-pack devices offer an alternative option to conventional plastic case IGBT modules whilst offering the same advantages such as:

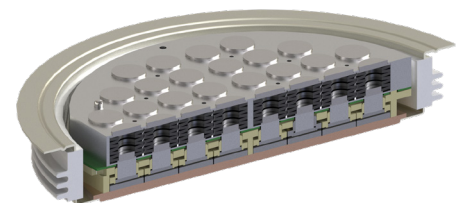
- Industry standard 10µs short circuit withstand
- High DC stability via advanced edge termination design and passivation
- Low switching losses and VCE(sat)

The use of advanced silver sintering die bonding technology and a hermetically-sealed ceramic housing means the Press-pack can also offer:

- Improved power cycling capability
- Operation even in the most hostile of environments
- Higher case-rupture ratings
- Compatibility with both new and existing clamping systems

With the incorporation of Dynamic Load-Balancing (DLB) technology, our Press-packs offer a unique design that ensures:

- Uniform clamping pressure on each chip during operation
- Enhanced device life time and reliability in service
- Compatibility with standard flatness tolerance heatsink components
- Reduced clamping system costs and/or complexity



A cross-section of a Dynex press-pack IGBT.